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10/621,611		07/18/2003	Yoichi Momose	116623	2899
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OLIFF & BERRIDGE, PLC				KIM, RICHARD H	
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Please find below and/or attached an Office communication concerning this application or proceeding.

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Paper No(s)/Mail Date _

2) Notice of Draftsperson's Patent Drawing Review (PTO-948)

3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)

Paper No(s)/Mail Date. ___

6) Other: _

5) Notice of Informal Patent Application (PTO-152)

DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-10 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamada et al. (US 6,013,339).

Referring to claim 1, 6, 7 and 10, Yamada et al. discloses an electronic device comprising a pair of substrates (Fig. 5, ref. 12a, 12b); a liquid crystal layer provided between the pair of substrates (13); and a sealing material bonding the pair of substrates to each other and enclosing the liquid crystal layer between the pair of substrate (3), the sealing material containing a photocurable component and a thermosetting component (col. 10, lines 25-27), the photocurable component having a curing rate in the range of from 60% to 95% (col. 16, lines 2-3), and the thermosetting component having a curing rate in the rage of from 60%-90% (col. 16, lines 5-6), at least one of a color filter and a metal wire (11) disposed at a position corresponding to the sealing material, at least one of a color filter and a metal wire at least partially blocking ultraviolet rays. Yamada et al. further discloses a method of manufacturing comprising applying an adhesive onto at least one of surface of the pair of substrates to form a closed shape in a region of the surface thereof (Fig. 8, ref. 3); disposing spacers on at least one of the surfaces of the pair of substrates (2); dripping liquid crystal onto at least one of the surfaces of the pair of

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substrates after the adhesive and spacers are disposed (13), bonding the pair of substrate to each other after the liquid crystal is dripped (col. 19, lines 19-23); and curing the adhesive after the bonding is formed, the adhesive being an uncured material which is formed to a sealing material by curing (col. 16, lines 10-15). Furthermore, Yamada et al. discloses the device wherein the liquid crystal is injected through a liquid crystal inlet (Fig. 2, ref. 9). However, the reference does not disclose that the *maximum* curing rate is in the rate of from 60% - 95%.

It would have been obvious to one having ordinary skill in the art at the time the invention was made for the maximum curing rate to be from 60% - 90% since Yamada et al. discloses that the proper curing rate prevents the generation of defect goods in production due to alignment dislocation, and therefore improves production efficiency. Therefore, an artisan having ordinary skill in the art would have known to determine the optimum curing rate of the respective material in order to achieve excellent production efficiency (col. 16, lines 1-15).

Furthermore, Yamada et al. does not disclose that the photocurable component at portions of the sealing material that correspond to the at least one color filter and a metal wire has a curing rate of less than 60%.

It would have been obvious to one having ordinary skill in the art at the time the invention was made for the photocurable component at portions of the sealing material that correspond to the at least one color filter and a metal wire has a curing rate of less than 60% since Yamada discloses the claimed bottom range of the curing ratio of 60%. Therefore, if the sealant is cured at a curing ratio of 60%, it is clearly apparent that the sealant above the wire, which would received less ultraviolet radiation than portions of the sealant not blocked by the wire, would have a curing ratio that is less than 60%.

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Referring to claims 2 and 3, Yamada et al. discloses a device wherein the sealing material includes a resin containing the photocurable component, a resin containing the photocurable component, a resin containing the thermosetting component, and a resin containing the photocurable component and the thermosetting component is the same molecular chain (col. 16, lines 28-67; col. 17, lines 1-10).

Referring to claim 4, Yamada et al. discloses the device wherein the photocurable component includes at least one of an acrylic group and a methacrylic group (col. 16, lines 28-37).

Referring to claim 5, Yamada et al. discloses that the thermosetting component includes an epoxy group (col. 4, lines 39-40).

Referring to claim 8, Yamada et al. discloses the method previously recited. Yamada et al. further discloses that the curing of the adhesive includes a light irradiation substep of curing the photocurable component (col. 16, lines 10-12), and the amount of light irradiation is 1000 to 6000 mJ/cm² (co. 17, lines 35-36).

Referring to claim 9, Yamada et al. disclose the method previously recited, and further discloses that the curing of the adhesive includes a heating substep of curing the thermosetting component. However, the reference does not disclose that the heating temperature and the heating time in the heating substep being set to 60 to 160 degrees Celsius and 20 to 300 minutes, respectively.

It would have been obvious to one having ordinary skill in the art at the time the invention was made for the heating time in the heating substep being to be set to 60 to 160 degrees Celsius and 20 to 300 minutes, respectively since the time and temperature in which to

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efficiently cure the adhesive is a result effective variable. Determining the optimum time and temperature to cure the adhesive would result in efficient curing.

Response to Arguments

3. Applicant's arguments with respect to the claims have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Richard H. Kim whose telephone number is (571)272-2294. The examiner can normally be reached on 9:00-6:30 M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Robert H. Kim can be reached on (571)272-2293. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Richard H Kim Examiner Art Unit 2871

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ANDREW SCHECHTER PRIMARY EXAMINER